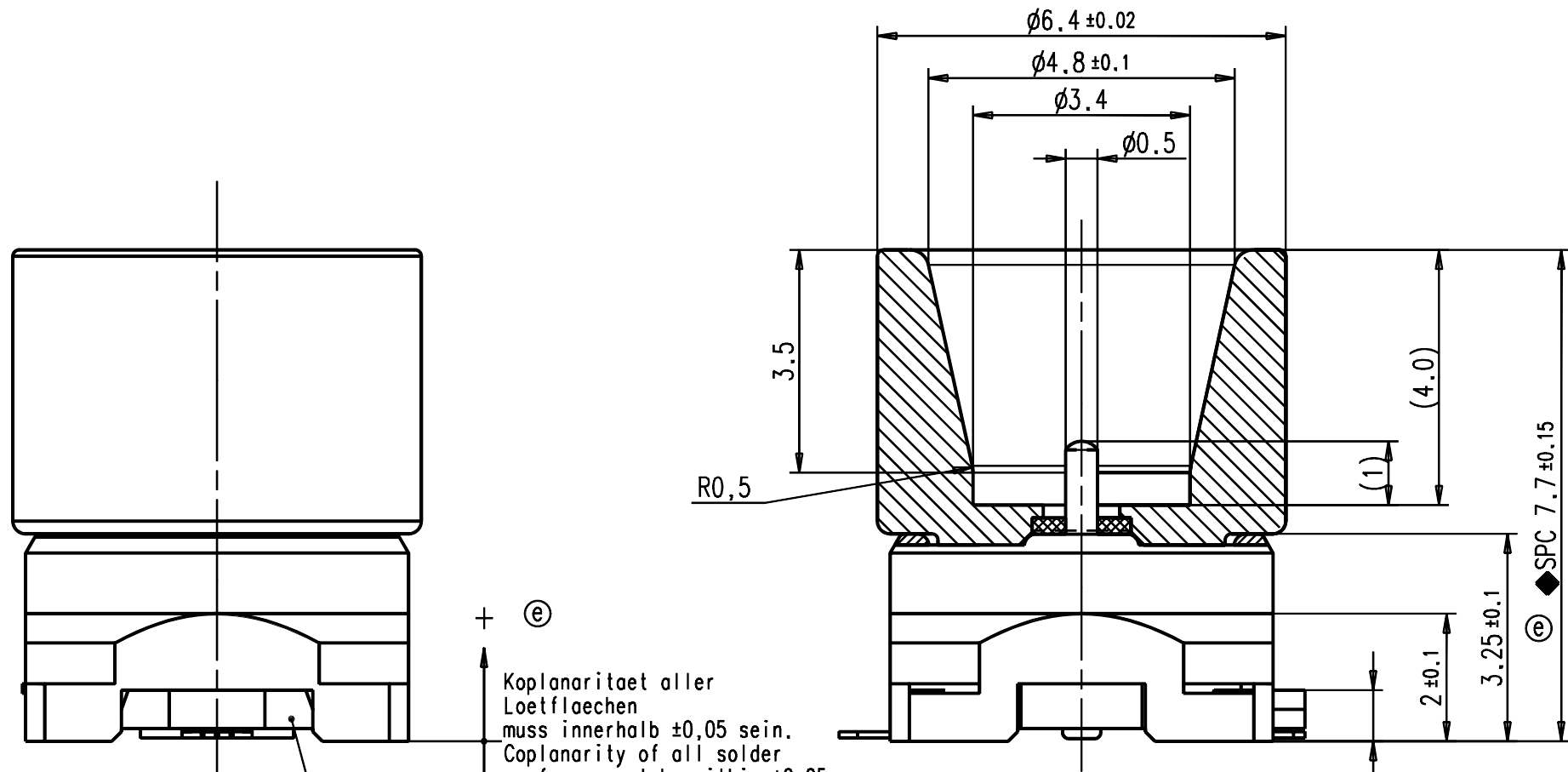


**Material und Beschichtung:**

Gehäuse	GD-ZnAl4Cu1	Optalloy & Flash Au
Isolierung	PA46	
Federn	CuBe2	Au
Restteile	CuZn	Au

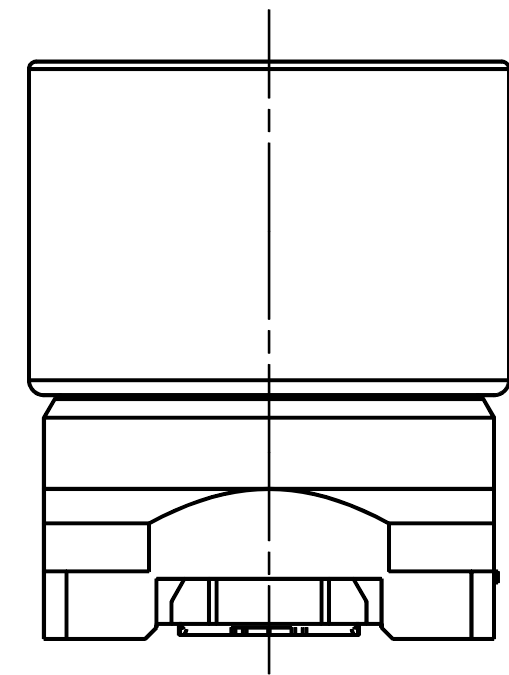
**Material and plating:**

Housing	GD-ZnAl4Cu1	Optalloy & Flash Au
Insulator	PA46	
Spring	CuBe2	Au
Other parts	CuZn	Au

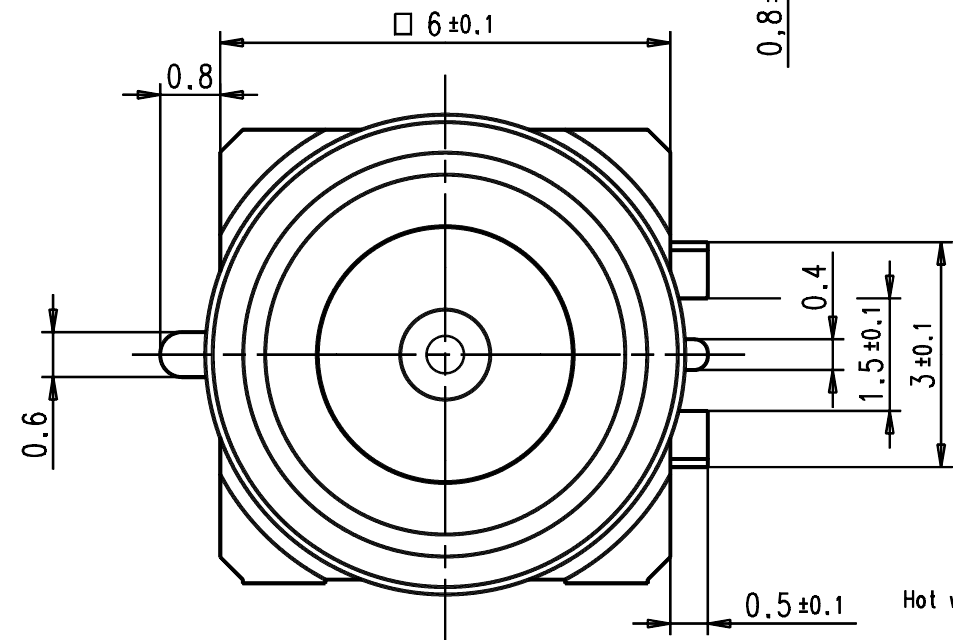


ⓔ Koplantitet aller Letflaechen muss innerhalb  $\pm 0,05$  sein. Coplanarity of all solder surfaces must be within  $\pm 0,05$

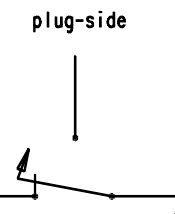
Orientation lug (2x)  
Orientierungsnasen (2x)



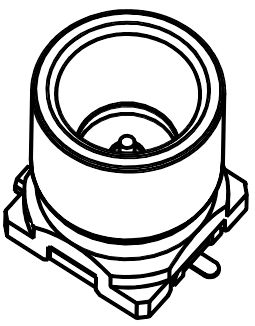
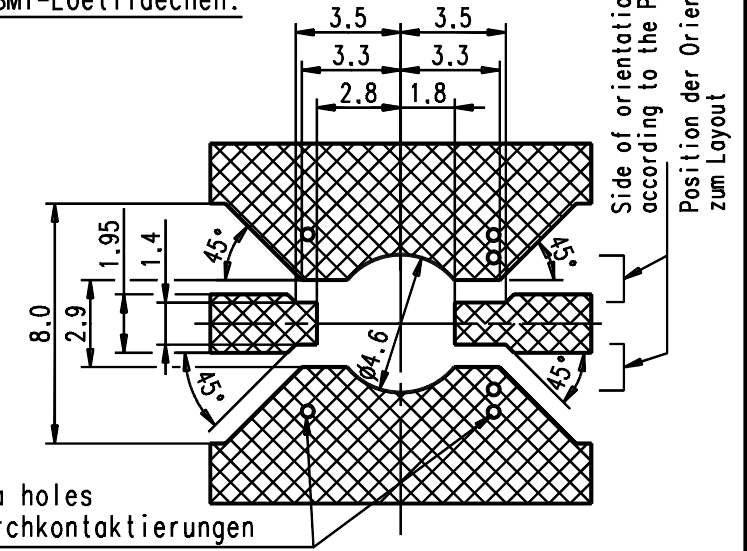
ⓔ Multilayer PCB under Switch have to be matched to 50 Ohm Multilayer-Layout unter Schalter muss auf 50 Ohm abgestimmt sein.



Switch function of front view:



SMT-Solderpad Layout proposal  
SMT-Letflaechen:



ⓔ Verpackung/Packaging:  
Blistergurt/Tape and reel:  
AGK 3357

ⓔ Anmerkung / Note:  
1. Maximal zulaessige Temperaturbelastung 250°C./  
Maximum heat wich can be applied to the switch is 250°C.

IMS CONNECTOR SYSTEMS					general tolerance ISO 2768 mH	scale: 10:1	
						Assembly instruction: Stripping dimension:	
EC_250_05	f	Coplanarity $\pm 0,05$	13.10.05	Mayer	date	name	SMT-Schalter SMT-Switch
EC_124_05	e	Überarbeitet	13.05.05	I.S.	generate	06.02.01 Berger	
716/02	d	Koplantitet	15.10.02	Berger	checked		
479/02	c	230°C-→250°C	30.08.02	Berger	Norm		
Entwurf	b	Vernietung hinzu	08.07.02	Berger	33898		
Entwurf	a	Daten ergaenzt	17.04.01	Berger			
nr.	rev.	alteration	date	name	3208.99.0030.00'		Rev. f